

Parylene Coatings:

Medical applications and R&D trends

EPHJ - Photonics 4 Luxury Coatings, June 2017

F.BOURGEOIS, PhD, R&D Project Manager



- 1. Comelec SA : Company Profile**
- 2. Parylene Coatings main features**
- 3. Medical applications**
- 4. R&D projects**
 - *High barrier multilayer coatings*
 - *Anti-bacterial Parylene Coating*
 - *Parylene LASER patterning*

- ❑ Founded in 1979, European leader in Parylene Coating.
- ❑ Coating service provider and equipment manufacturer
- ❑ 20 People
- ❑ 10 coaters at Comelec / 2000 batches deposited per year
- ❑ 55 equipments worldwide



➤ Strong involvement in R&D projects :

✓ European projects :

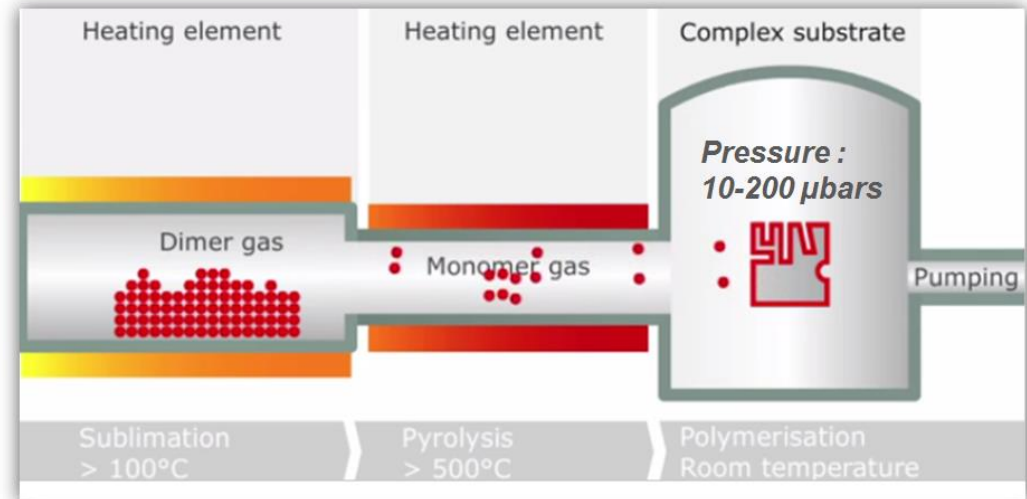


✓ CTI (Swiss funded projects)



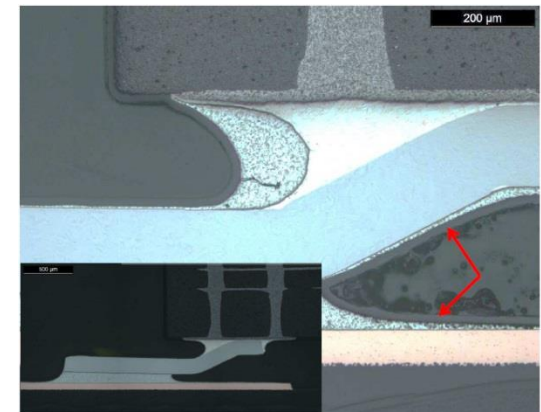
□ An unique polymer process...

- Process patented in 1967 (Gorham, USA) => first application : PCBs in 70's (Union Carbide Corp.)
- Vacuum Process known as "Vapor Deposition Polymerization", very similar to CVD.
- Typical thicknesses : 1-50 μm (control possible from 50 nm)



□ ...with unique advantages

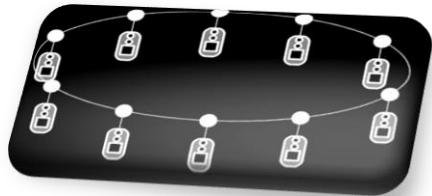
- Very high **penetration ability** : near 100% conformal coating
=> *coating of very complex 3D items is possible*
- Near **room temperature** process
=> *stress free coating*
=> *no damage on heat sensitive parts* (often at the very end of the manufacturing line)



Parylene success is not only a question of material properties, this is also due to a unique process !

- 2 kinds of tools to deposit Parylene coatings:

Static Coating



- ✓ *Almost no size / shape limitation*
- ✓ *Fragile parts handling*
- ✓ *Manual disposal of the parts (time consuming)*

Tumble Coating



- ✓ *No contact points*
- ✓ *Very large volume production / very low cost*
- ✓ *Limited by the size / shape / mechanical resistance*

- Some examples of standard coating equipments...

C-50S



C-25S-Plasma



C-22T

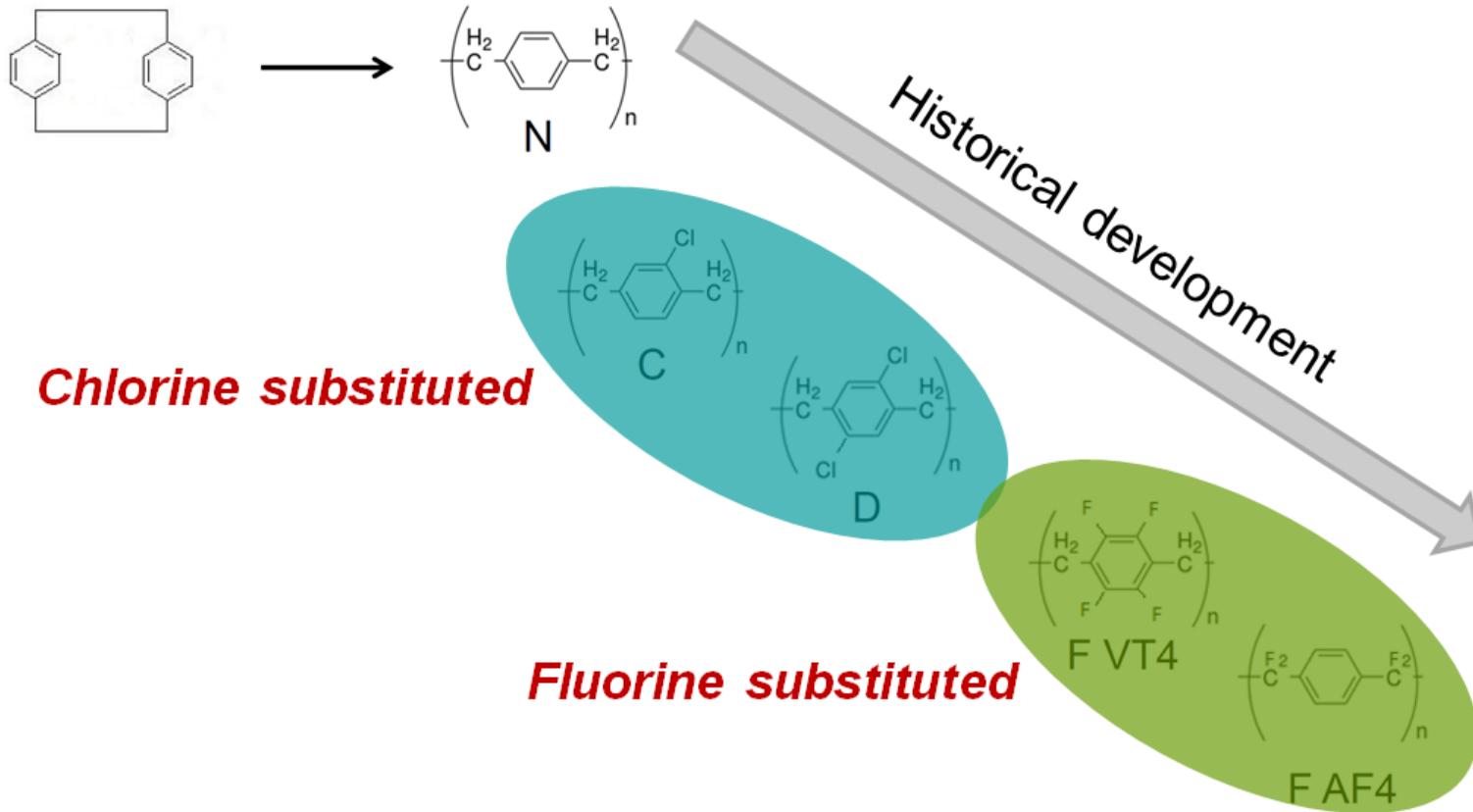


- Featured options:

- In situ plasma process (ICP, CCP, MW)
- Vaporization modules (adhesion promotor, etc...)
- Chamber heating / cooling
- Automated LN2 filling

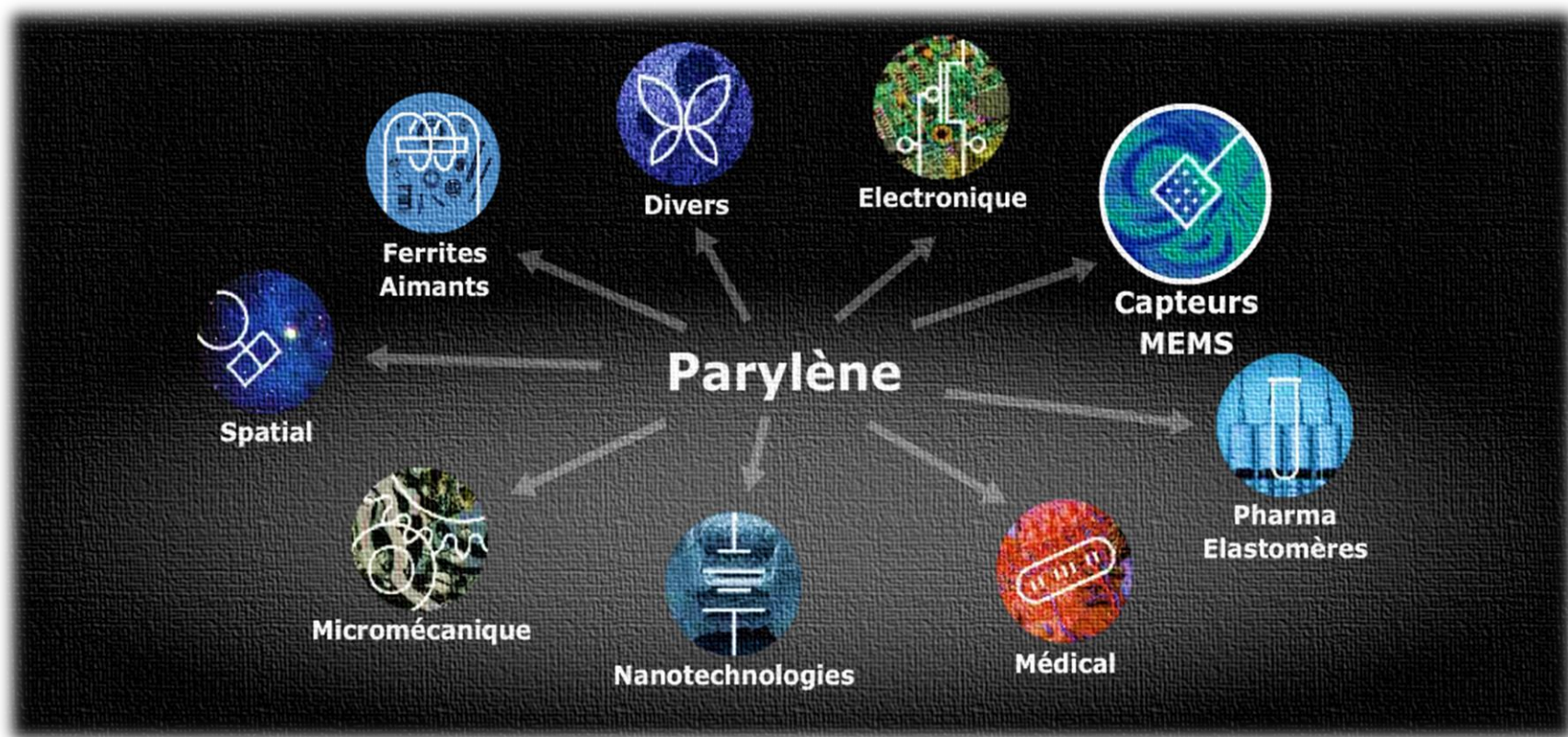


- 5 main chemistries of “PARYLENE”: poly(para-xylylene) polymers



- ❑ **Most popular properties leading to success of Parylene :**
 - **Chemically neutral with most substances.**
 - **Biocompatible, and biostable (FDA approved, USP Class VI).**
 - **Very good dielectric material.**
 - **Solid lubricant (ease of slipping for medical devices)**
 - **Hydrophobic**
 - **Very good barrier properties among polymeric materials**
 - **Almost 100% conformal coating , without pinholes.**
 - **High to very high thermal stability (up to 450°C)**
 - **Transparent film in the visible wavelengths**

3. Medical Applications



❑ Historical first Parylene application

✓ PCB coating :

- Protects against *moisture and oxygen*.
- Protects against *corrosive agents*.
- Avoids electrical damage of chips.
- Prevents from Tin whiskers related damages.
- Enhances mechanical reliability (vibration)

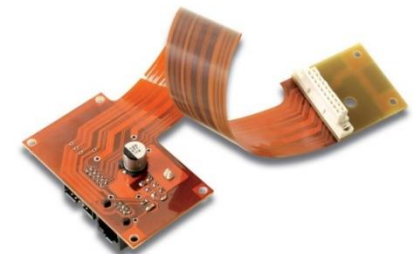


=> Improved reliability in harsh environment

Especially for Military and aerospace applications.

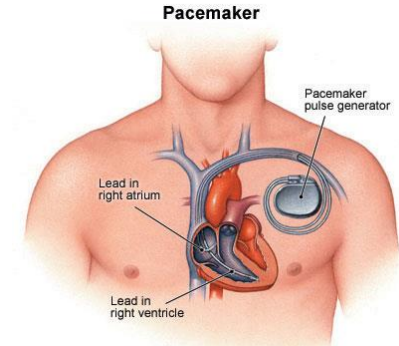
Evolution to flex PCBs (especially for medical applications) :

- As substrate or packaging layer



✓ **Implanted electronic devices (Pacemakers, Micropumps, , cochlear implants, sensors...)**

- *Improves reliability. Used as a complement to Titanium housing (diffusion barrier layer, protection against dielectric breakdown, wiring mechanical reinforcement, etc..)*
- *Passivates materials to prevent from allergen reactions*



✓ **Catheters, canulae, wirings, stents, etc...**

- *Dry lubricity makes insertion easier*



✓ **Rubbers seals / O-rings / silicones parts**

- *Dry lubricity facilitates insertion / gliding*
- *Hydrophobicity enhances performances (fluid management)*
- *Brings chemical inertness to elastomers (prevents from elastomer damage or additives releases)*



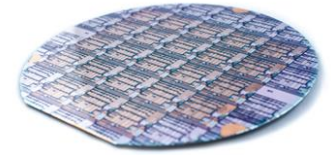
✓ **Polymers containers (pharmacology)**

- *Brings chemical inertness and keep pharmaceutical fluids pure*

✓ **Implantable glass tags :**

- *improves and accelerates tissue adhesion*

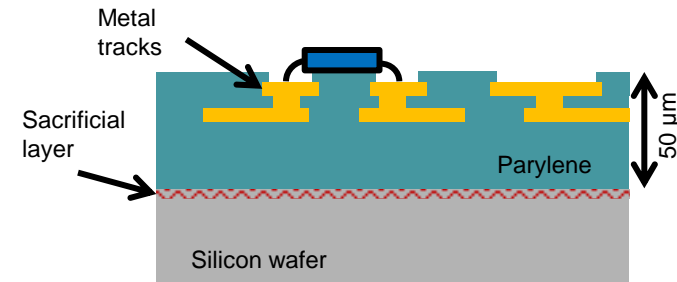
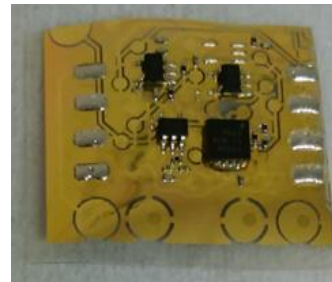
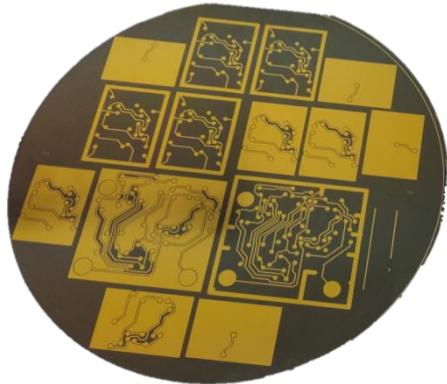




✓ More and more Medtech devices built at the wafer scale, and so are deposited the Parylene layers.

❑ European Project 2015-2018 : InForMed (ECSEL JU funding)

○ Smart Body Patches : electronics on flexible Parylene substrate



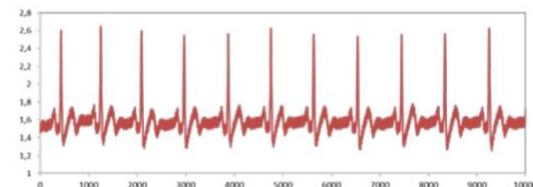
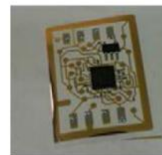
❑ Manufacturing of free standing Parylene based PCBs

❑ Processing on Silicon wafers (100mm)

- Up to 3 level of metals (Au) including interconnexions
- ICs bonding / brazing
- Parylene substrate release (overall thickness of~ 50microns)

F. Bourgeois (Comelec SA), A. Bongrain (Bodycap), PA Chapon (Bodycap), G. Lissorgues (ESIEE), L. Rousseau (ESIEE)

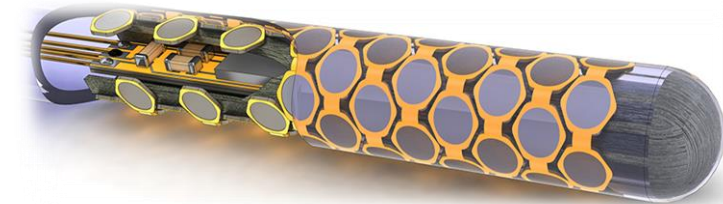
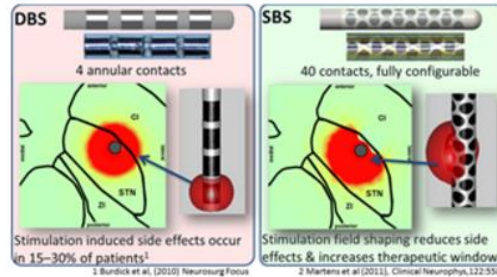
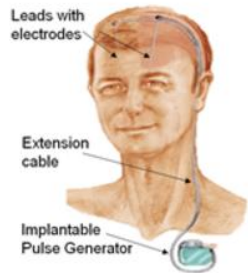
❑ First functional demonstrators (flexible ECG device)



ECG on parylene

❑ European Project 2015-2018 : InForMed (ECSEL JU funding)

○ Steering Deep Brain Stimulator



Source: www.informed-project.eu

Left: State-of-the-art DBS system; Right: clinical trials have proven that the segmented steering probe of SAPIENS can prevent side effects normally associated with DBS.

❑ Coating for long term implantable devices.

❑ Development of adhesion strategies on a single device combining “critical” materials (PI, noble metals, ...)

- ✓ Adhesion evaluation using delamination tests or IDE . Before/After PBS soaking or during PBS soaking
- ✓ Interface control using plasma and plasma polymers process and / or adhesion promotors

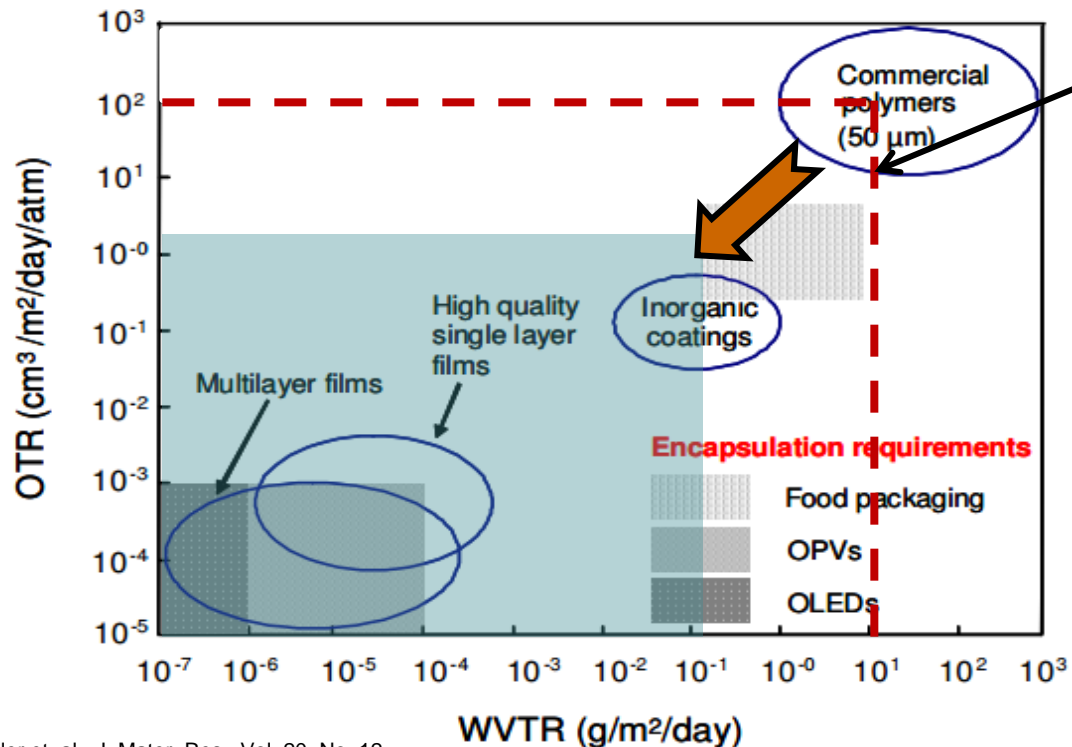
❑ Toward a Flex-2-Rigid technology with Parylene (instead of Polyimide)

- High Barrier Multilayer Coating**
- Anti-microbial Parylene**
- Parylene LASER ablation**
- Development of Advanced Parylene Coaters for wafers processing in clean rooms**
- Parylene adhesion reliability**
-**

□ High Barrier Multilayer Coating

Goal : Develop a parylene based multilayer coating with enhanced barrier properties

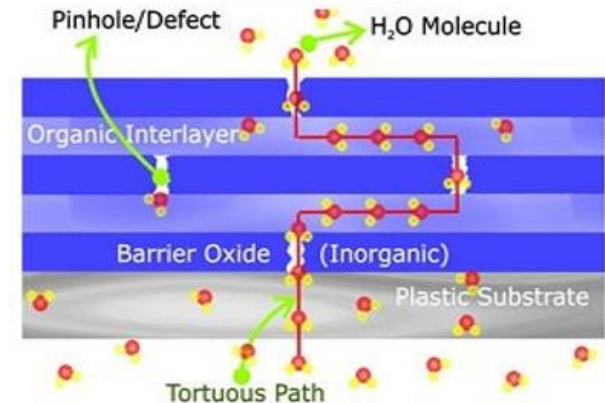
General approach: combine ceramic-like layer(s) with tight structures and Parylene



Par.C 25 μm :

WVTR \Rightarrow ~ 4 g/m²/day

O₂TR \Rightarrow ~ 120 cm³/m²/day



□ High Barrier Multilayer Coating

State of the art : process often developed on silicon wafers or on free standing packaging films

Producer	Encapsulation Structure	Number of layers	W V T R 23°C, 50% RH (g.m ⁻² .day ⁻¹)	Strain at failure (%)
Vitex (Barix)	[acrylate/Al ₂ O ₃] ₄	7 + planarization	~ 1 × 10 ⁻⁶	0.8
Philips (NONON)	[SiN _x /SiO _x] _n	'12' + topcoat	3.6 × 10 ⁻⁶	1.0
GE (graded UHB)	[SiN _x /SiO _x] _n	'5'	8.6 × 10 ⁻⁶	?
Applied Materials	[SiN/lacquer] ₂	4 + planarization	~ 10 × 10 ⁻⁶	1.0
3M	[oxide/polymer] ₂	4 + planarization	~ 0.5 × 10 ⁻⁶	?
Picosun	ALD (batch)	1	~ 1 × 10 ⁻⁶	?
Tera-Barrier	[nanocompos./oxide] ₂	5 + planarization	~ 1 × 10 ⁻⁶	?
Rolic	[SiN _x /polym nanocomp.] _{1,2}	2 or 4	~ 10 ⁻⁵ – ~ 10 ⁻⁶	?
Fraunhofer	[ormocer/ZTO] ₂	4 + planarization	70 × 10 ⁻⁶	?

Trade-off between barrier ultimate barrier properties and strain at failure !

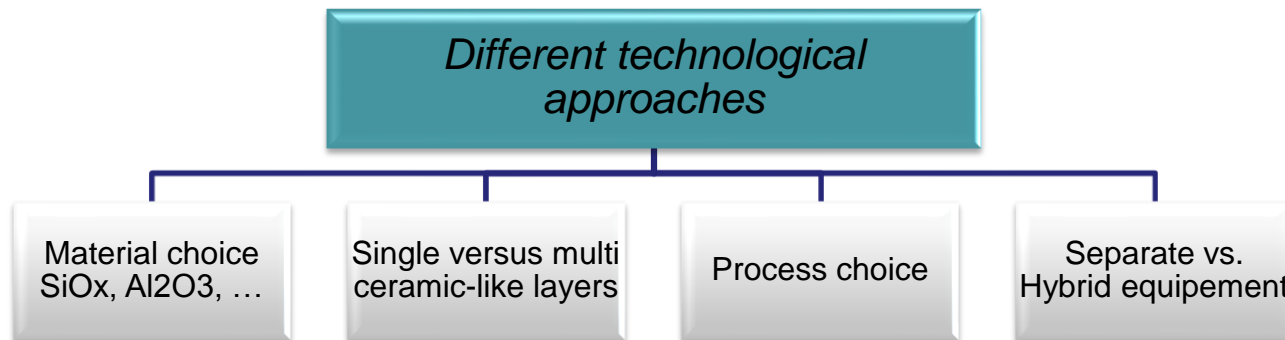
Comelec goals :

- ✓ WVTR < 10⁻² g/(m².day) for a 10µm multilayer coating (x 100)
- ✓ Strain at failure > 2%
- ✓ Industrial scale process for 2D and 3D parts (large reactors)
- ✓ Low temperature process (<100°C)

□ High Barrier Multilayer Coating

Key Factors :

- *Statistics of defects and configuration to hinder related effects (cracks, particles, ...)*
- *Materials quality : intrinsic diffusion*
- *Interface control : stress, adhesion.*



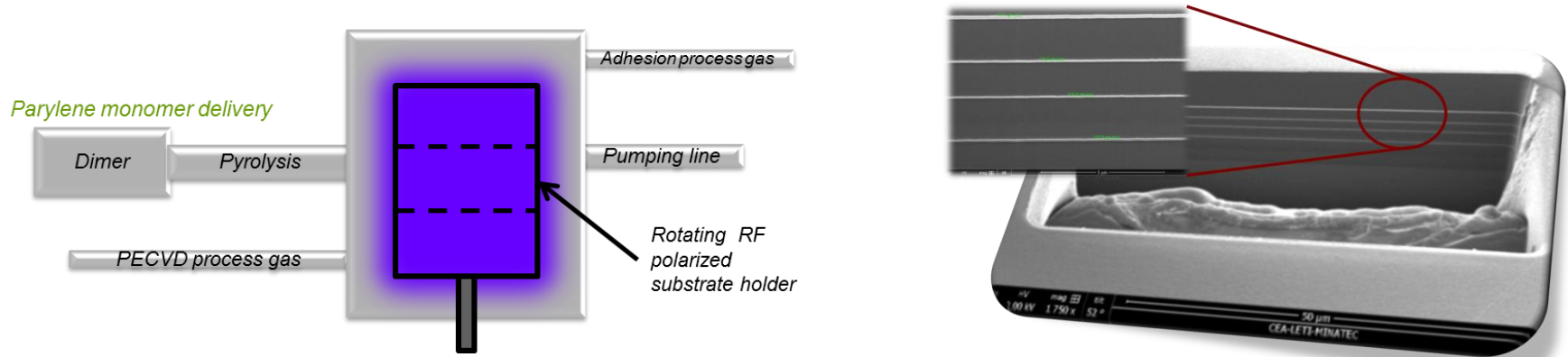
No universal choice for all applications => Comelec develops different approaches

Advantages of Parylene:

- Ability to «heal» defects thanks to exceptional conformality:
 - Particles immobilization
 - Cracks / pinholes penetration
- Low stress coating thanks to low temperature process (20-50°C) / no shrinkage

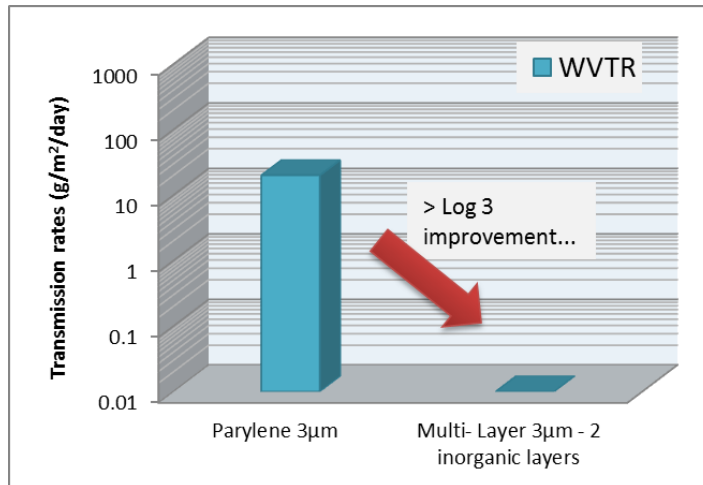
High Barrier Multilayer Coating: results / status

- Hybrid equipment including Capacitive Coupled Plasma (CCP) :

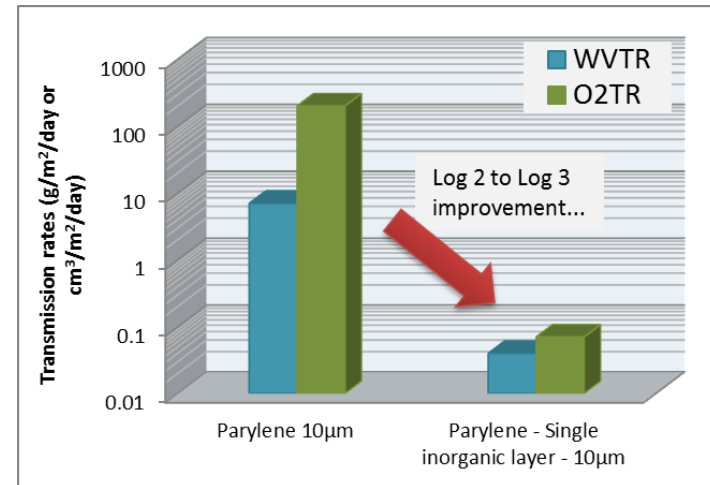


- Proof of concept validated, first Parylene based multilayer with enhanced WVTR (3 logs !!)

Hybrid process



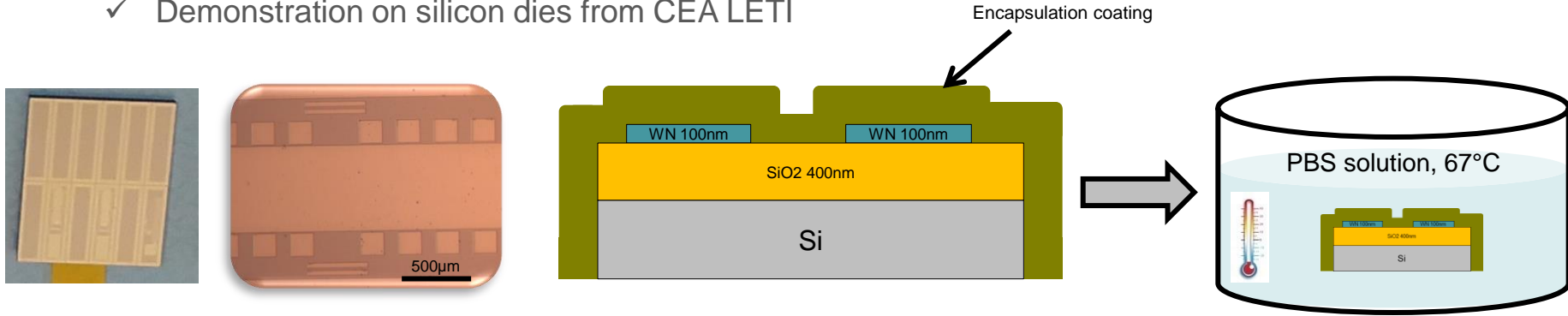
Subsequent processes, single ceramic layer



High Barrier Multilayer Coating: results / status

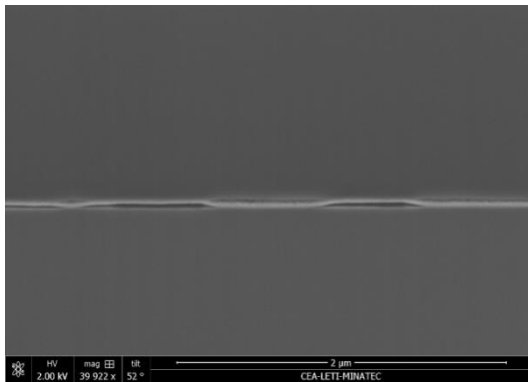
- Hybrid equipment – several SiOx layers approach:
 - ✓ Demonstration on silicon dies from CEA LETI

F. Bourgeois (Comelec SA),
JC. Souriau (CEA-LETI),
C. Quiniou (CEA-LETI)



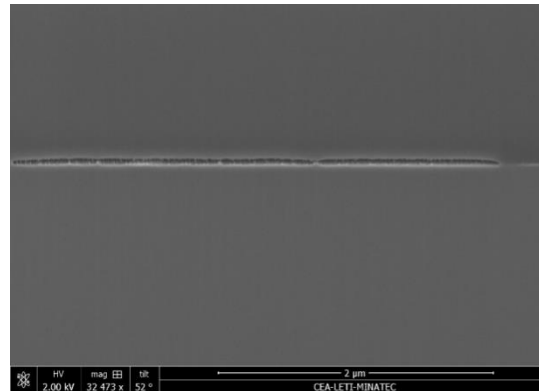
➡ Results after 4 months soaking:

Par. AF4 – 15 μm



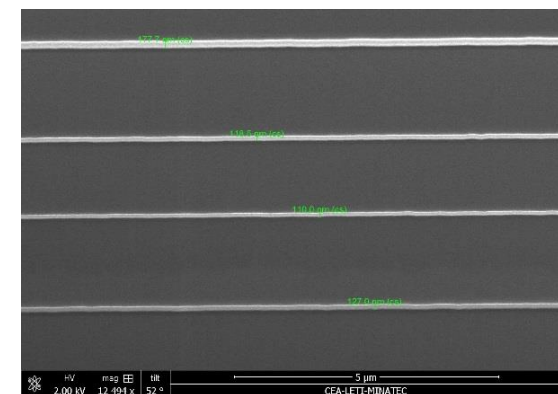
- ✓ WN not dissolved
- ✓ Adhesion NOK

Par. C – 15 μm



- ✓ WN not dissolved
- ✓ Adhesion NOK

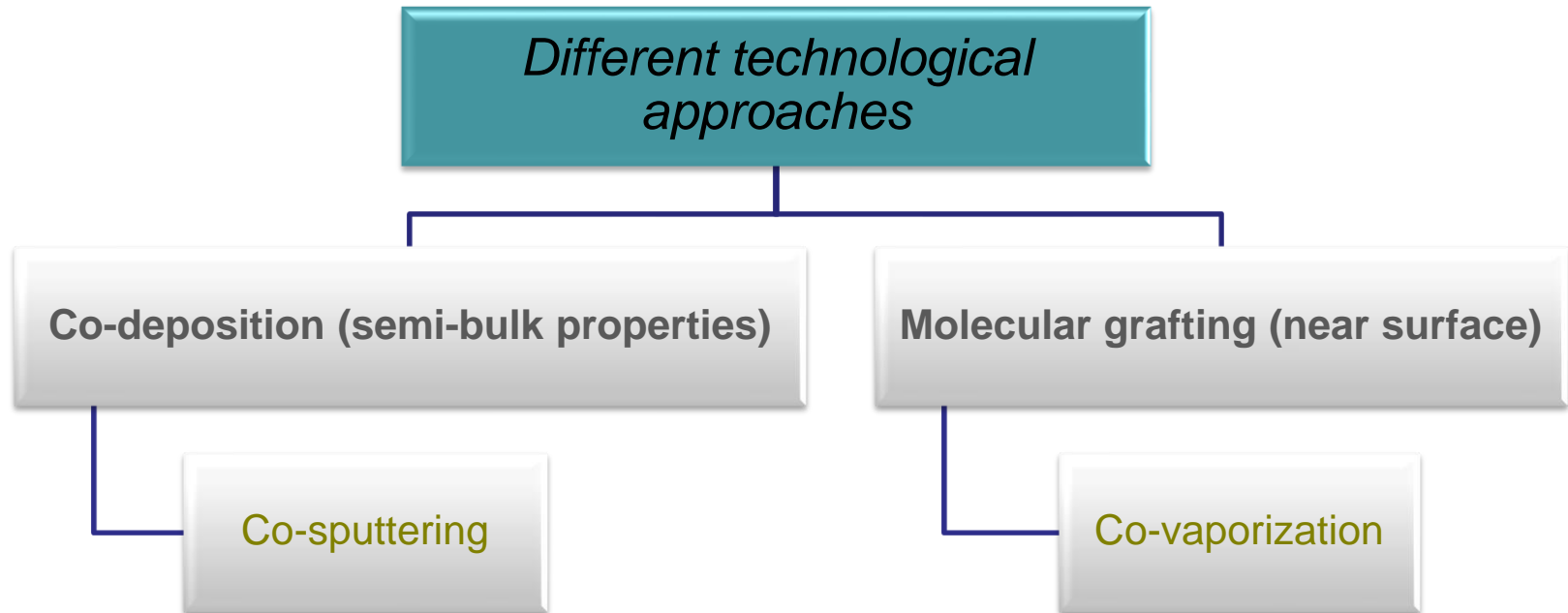
SiOx/ParC Multilayer – 15 μm



- ✓ WN not dissolved
- ✓ Adhesion OK

□ Anti-microbial Parylene

Goal : bring an anti-bacterial functionality to the parylene coating



Challenges:

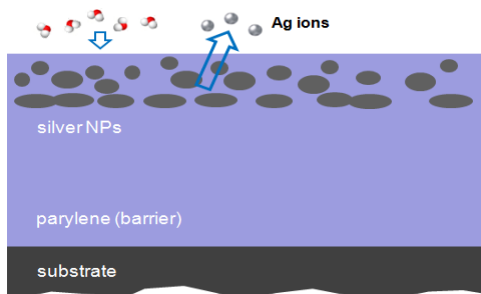
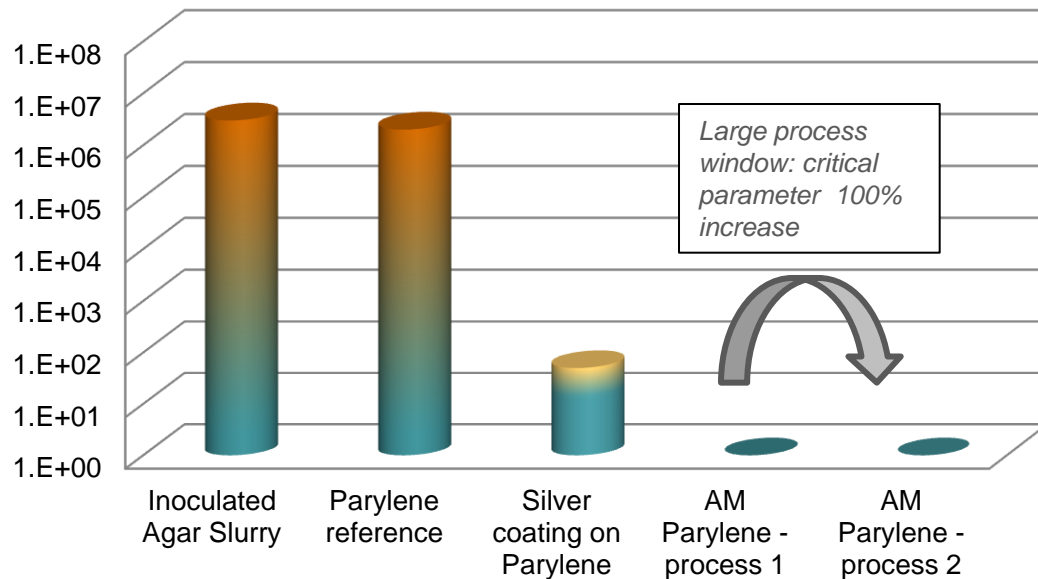
- control anti-microbial efficiency over time and biocompatibility*
- develop a scalable industrial process*

Co-sputtering approach – Silver / Parylene composite

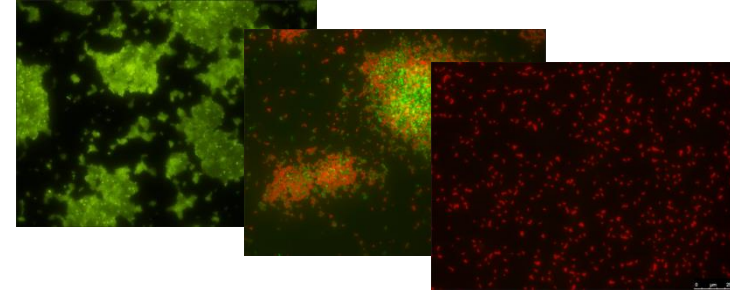
ASTM Standard Test Method



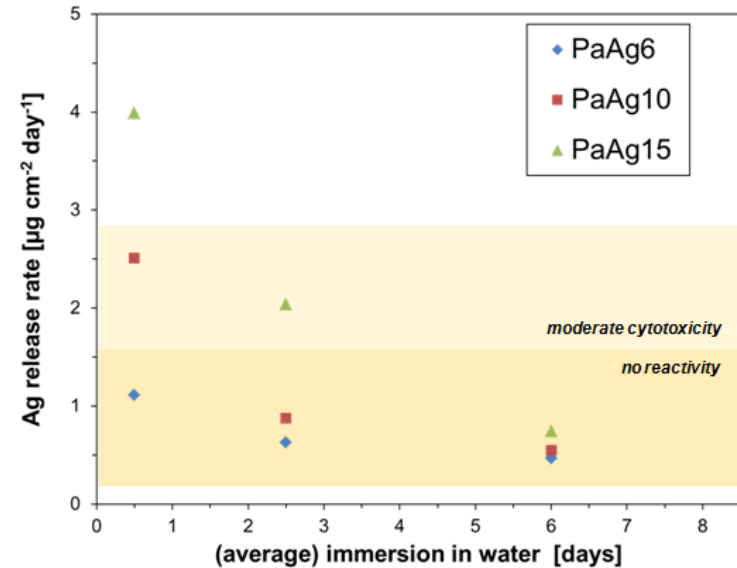
- *Staphylococcus aureus* (DSMZ No. 20231) suspension in agar slurry
=> 10^6 colony forming units (cfu)/ml
- Incubation at 37°C, non-shaking, 24 hours
- Compare activity value (Control to test count)



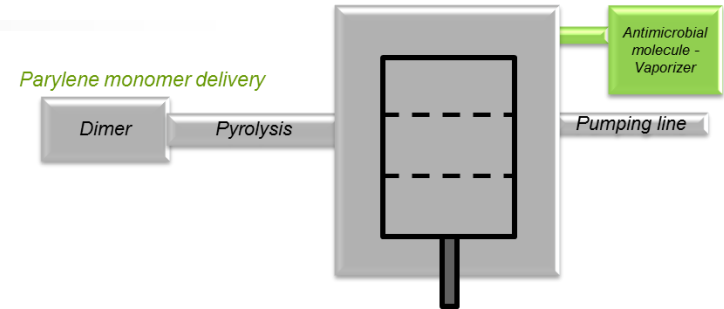
LIVE / DEAD staining tests



Ag release versus time



□ Grafting of anti-microbial molecules (e.g. ammonium compounds)

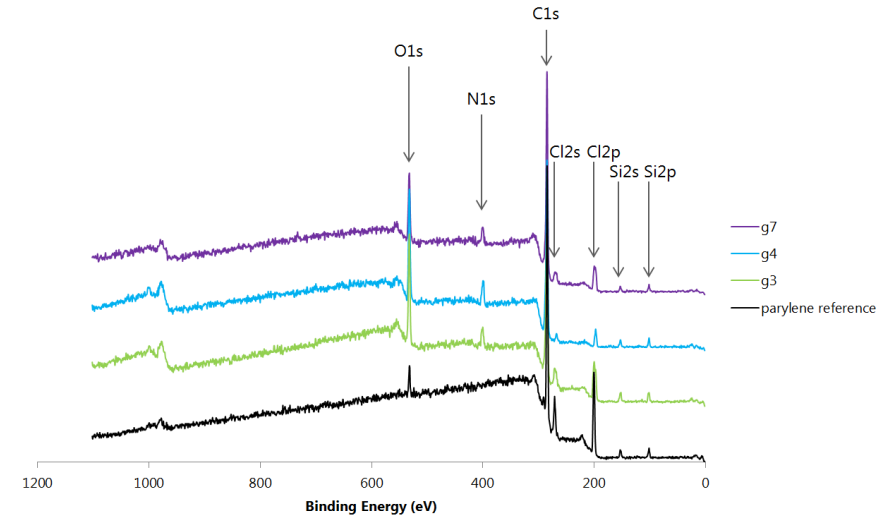
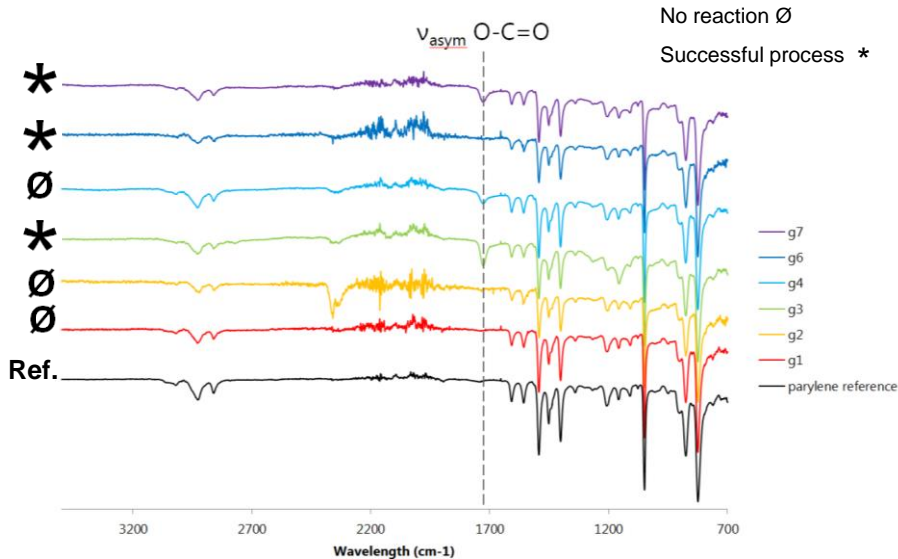


FTIR analysis :

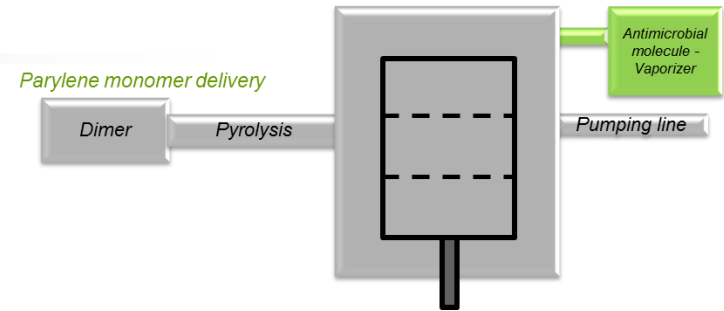
- O-C=O signature indicates presence of the antimicrobial molecule in the coating

XPS analysis :

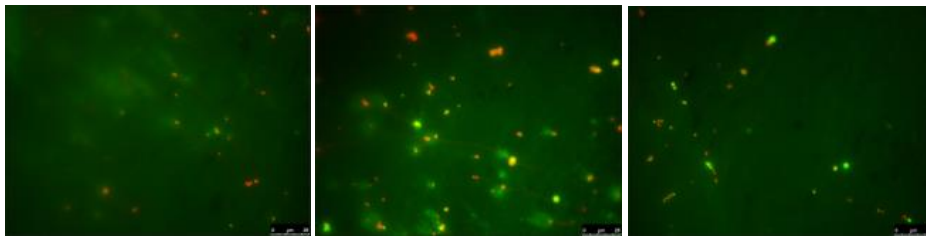
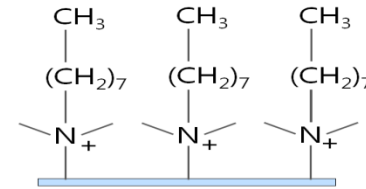
- N presence indicates presence of antimicrobial compound at the parylene surface



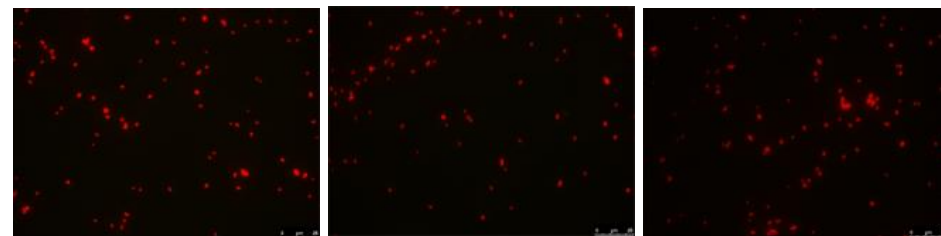
- Grafting of anti-microbial molecules
(e.g. ammonium compounds)



LIVE / DEAD staining tests



Parylene reference



“Ammonium” grafted Parylene

- Promising process allowing combination of antimicrobial molecule with Parylene
- Antimicrobial activity demonstrated
- Next steps :
 - Process industrialization
 - Applications demo

□ Development of Parylene LASER Ablation / patterning

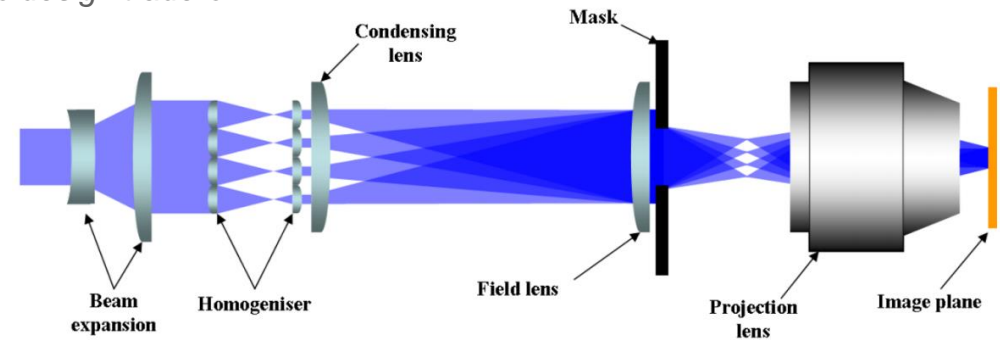
Goal : *replace and going further than manual masking*

- ✓ *Increase production yields : decrease costs*
- ✓ *Less mechanical sollicitation: better quality*
- ✓ *Fullfill miniaturization requirements : no design trade-off*



Materials Science & Technology

Source: P. Hoffmann, Empa Thun



Experimental set-up:

- *KrF Excimer LASER, 248nm => Photo-chemical ablation (instead of photo-thermal ablation)*
- *Beam homogenizer*
- *Mask projection system => very high productivity possible for large surfaces / high volume production*
- *Fluences: 200-500 mJ/cm²*
- *Repetition rate (frequency): 1-50 Hz*

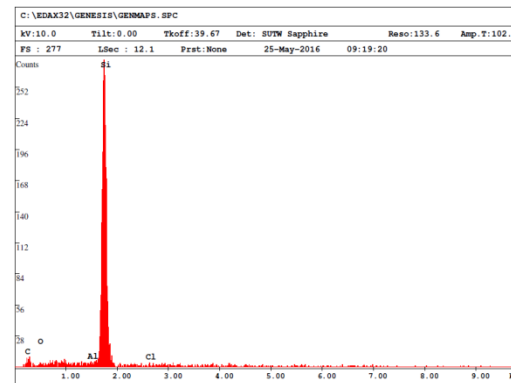
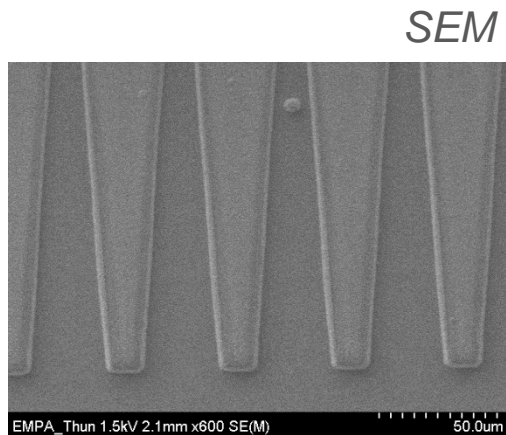
Samples :

- *Parylene AF4 12µm on Si wafer*
- *Parylene AF4 12µm on glass*
- *Parylene C 6µm on Si wafer*

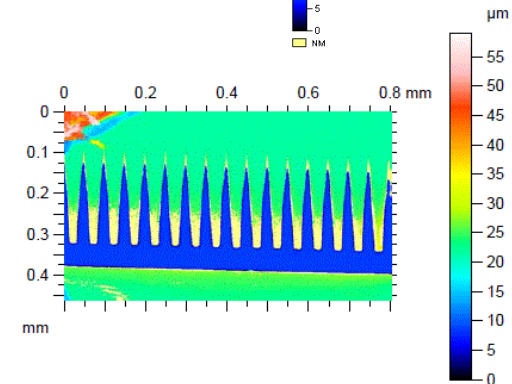
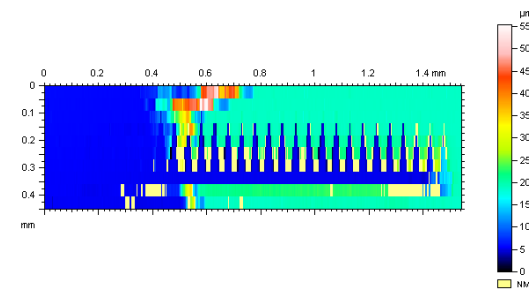
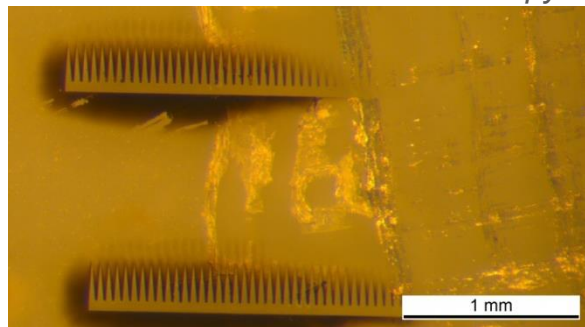
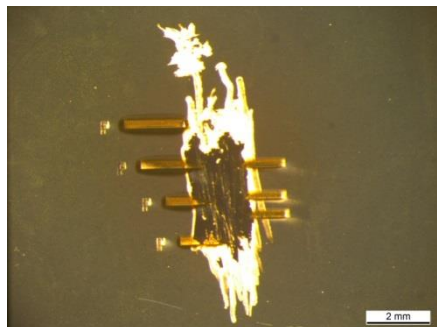
Development of Parylene LASER Ablation / patterning

Characterization:

Par. C - 6 μ m - on Si



Par. AF4 - 12 μ m - on Si



❑ Development of Parylene LASER Ablation / patterning

Promising results:

- The Excimer laser repetition rate (frequency) does not change the ablation behaviour between 1Hz to 50 Hz. This indicates no strong thermal accumulation effect.
- No delamination of the Parylene film (typical failure when high thermal load or «burning»)
- No ablation of Silicon and glass wafers, even for large thickness (12 μm)
- Ablation leads to pattern resolution below 3 micrometers.
- High ablation rate in the range of $\sim \mu\text{m}/\text{sec}$

Observations to work on:

- Brown debris is deposited around the ablation regions. Can be removed largely in isopropanol ultrasonication.
- Residues on the Si substrate on the ablated floor remains in all cases even with very large number of shots.



Your contacts :

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✓ PCB coating :

- Protects against *moisture and oxygen*.
- Protects against *corrosive agents*.
- Avoids *electrical damage* of chips.
- Prevents from Tin whiskers related damages.
- Enhances mechanical reliability (vibration)



=> Improved reliability in harsh environment

Especially for Military and aerospace applications.

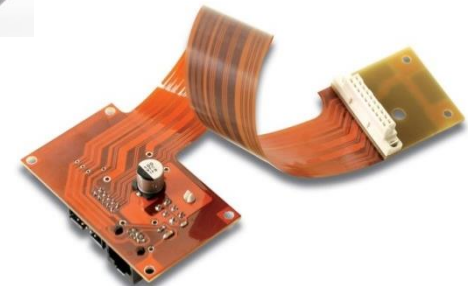
✓ Coil / Cores insulating

- Dielectric layer.



✓ Flex PCBs :

- As substrate or packaging layer



- ✓ **Solid lubricant :**
 - *reducing the wear of parts in friction (only with relatively small stress)*

- ✓ **Anti-tarnishing:**
 - *avoiding corrosion related damages (silver tarnishing, ...)*

- ✓ **Cohesion media for sintered parts :**
 - *sealing porosities, reducing brittleness*
 - *particle immobilization*

- ✓ **Elastomer lubrication / protection:**
 - *reduce friction*
 - *protect against chemical damages*

